



40V N-Channel Enhancement Mode MOSFET

Voltage

40 V

Current

85 A

Features

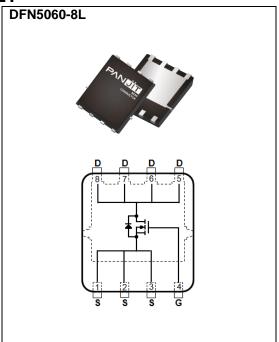
- RDS(ON), VGS@10V, ID@20A< $5.3m\Omega$
- RDS(ON), VGS@4.5V, ID@20A<7.4m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.08 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETE	SYMBOL	LIMIT	UNITS		
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current ^(Note 3)	T _C =25°C		85	A	
	T _C =100°C	l _D	60		
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	340		
Power Dissipation	T _C =25°C	Po	68	W	
	T _C =100°C		34		
Continuous Drain Current(Note 4)	T _A =25°C	I _D	18.7	А	
	T _A =70°C		15.6		
Power Dissipation	T _A =25°C	7	3.3	10/	
	T _A =70°C	P _D	2.3	W	
Single Pulse Avalanche Energy ^(Note 5)		Eas	90	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	$R_{ heta JC}$	2.2	°C/W	
	Junction to Ambient	$R_{\theta JA}$	45		





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	40	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =50uA	1.1	1.7	2.3	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	4.2	5.3	mΩ
		V _{GS} =4.5V, I _D =20A	-	5.7	7.4	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Dynamic ^(Note 6)						
Total Gate Charge	Qg	V _{DS} =32V, I _D =20A, V _{GS} =10V	-	20	-	nC
Gate-Source Charge	Qgs		-	3.1	-	
Gate-Drain Charge	Q_{gd}		-	6.4	-	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHz	-	1320	-	pF
Output Capacitance	Coss		-	250	-	
Reverse Transfer Capacitance	Crss		-	30	-	
Gate resistance	Rg	f=1MHz	-	0.8	-	Ω
Turn-On Delay Time	td _(on)	V _{DS} =32V, I _D =20A, V _{GS} =10V, R _G =3Ω (Note 2)	-	8	-	ns
Turn-On Rise Time	tr		-	36	-	
Turn-Off Delay Time	td(off)		-	19	-	
Turn-Off Fall Time	tf		-	55	-	
Drain-Source Diode			_			
Diode Forward Current	Is	T _C =25°C	-	-	85	Α
Pulsed Diode Forward Current	I _{SM}		-	-	340	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.85	1.3	V
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	-	43	-	ns
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	34	-	nC

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{eJC}=2.2°C/W.
- 4. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I_{AS}=19A, V_{DD}=25V, V_{GS}=10V, Starting T_J=25°C.
- 6. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

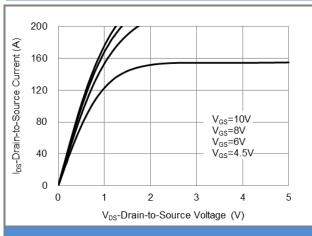


Fig.1 On-Region Characteristics

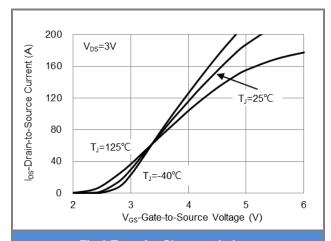


Fig.2 Transfer Characteristics

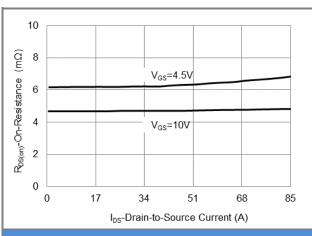


Fig.3 On-Resistance vs. Drain Current

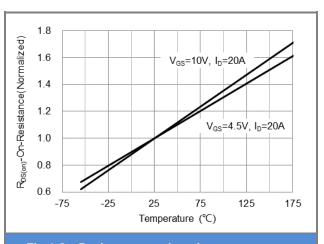
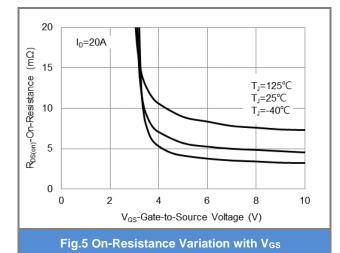
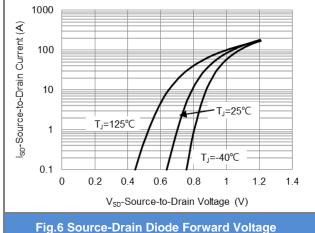


Fig.4 On-Resistance vs. Junction temperature









TYPICAL CHARACTERISTIC CURVES

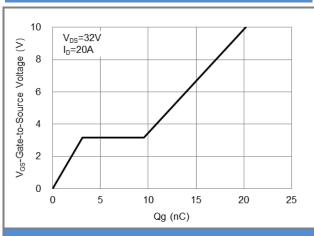


Fig.7 Gate-Charge Characteristics

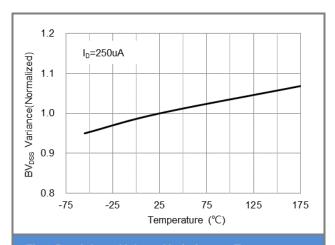


Fig.8 Breakdown Voltage Variation vs. Temperature

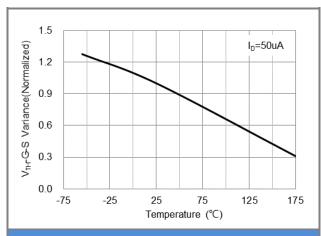


Fig.9 Threshold Voltage Variation with Temperature

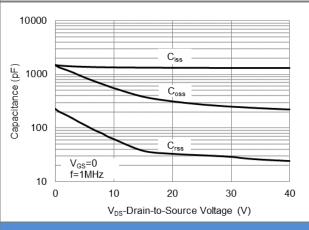
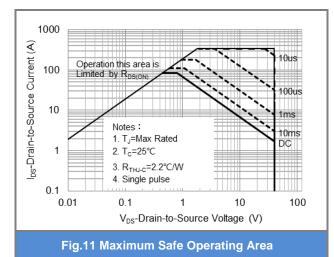


Fig.10 Capacitance vs. Drain-Source Voltage



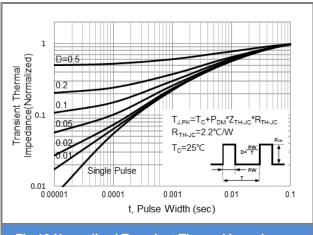


Fig.12 Normalized Transient Thermal Impedance

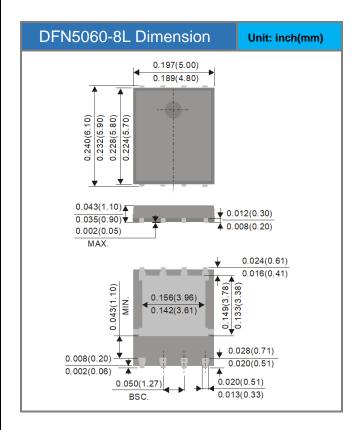


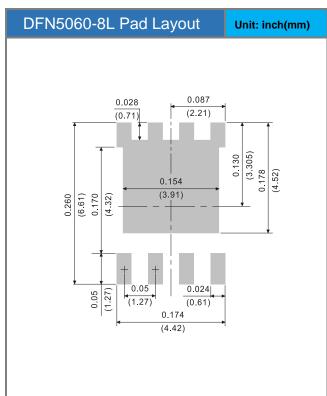


Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
PJQ5546-AU_R2_002A1	DFN5060-8L	3K pcs / 13" reel	Q5546	Halogen free RoHS compliant

Packaging Information & Mounting Pad Layout









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